ī.	Hits	Search Text	DB	Time stamp
Number				
1	3	5198964.pn.	USPAT;	2002/06/24
			US-PGPUB;	22:05
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/06/24
2	4650728	gold au	USPAT;	2002/06/24
	1		US-PGPUB;	22:05
			EPO; JPO;	
			DERWENT;	
]		IBM_TDB USPAT;	2002/06/24
3	1	5198964.pn. and (gold au)	USPAT; US-PGPUB;	2002/06/24
	·		EPO; JPO;	22:11
			DERWENT;	
			IBM TDB	
		1 1 1 (1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USPAT;	2002/06/24
4	1134943	lead leadframe (lead adj frame)	US-PGPUB;	22:12
			EPO; JPO;	22.12
			DERWENT;	
			IBM TDB	
_	5076	(lead leadframe (lead adj frame)) with	USPAT;	2002/06/24
5	5876	(plated plating covered layer) with (gold	US-PGPUB;	22:13
			EPO; JPO;	22.13
		au) · • • •	DERWENT;	
			IBM TDB	
6	997	((lead leadframe (lead adj frame)) with	USPAT;	2002/06/24
0	1	(plated plating covered layer) with (gold	US-PGPUB;	22:13
		au)) same solder	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	2119145	semiconductor die chip ic dice	USPAT;	2002/06/24
		(integrated adj circuit)	US-PGPUB;	22:15
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	496	package and (((lead leadframe (lead adj	USPAT;	2002/06/24
		frame)) with (plated plating covered	US-PGPUB;	22:15
		layer) with (gold au)) same solder)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/06/24
9	462	(semiconductor die chip ic dice	USPAT;	2002/06/24
		(integrated adj circuit)) and (package	US-PGPUB;	22:10
		and (((lead leadframe (lead adj frame))	EPO; JPO;	
		with (plated plating covered layer) with	DERWENT;	
		(gold au)) same solder))	IBM_TDB	